KRUSE
ADHESIVE TAPE, INC.

PRODUCT DATA SHEET

K-830

1 MIL POLYIMIDE FILM TAPE

APPLICATIONS

Designed for very high temperature masking applications. Ideal for masking the gold fingers on printed circuit boards during the wave solder process. Temperature ranges from -100° to 500° F (-73°to 260° C).

FEATURES/BENEFITS

- The high performance silicone adhesive system features excellent adhesion to printed circuit boards during the wave soldering process with ***clean one piece removal***.
- The high temperature polyimide film ***absorbs heat*** without shrinking or losing its construction integrity.
- K-4428 is thin and conformable, with outstanding puncture, tear and abrasion resistance at elevated temperatures.
- Also available in die-cut form for spot masking.

TECHNICAL DATA

Backing material : 1 mil Polyimide Film
Adhesive : Silicone
Color : Amber
Tape thickness : 2.8 mils/0.056 mm
Elongation : 52%
Adhesion to steel : 25 oz. per inch/2.8 N/cm
Tensile strength : 30 lbs. per inch/44 N/cm
Temperature rating : 180° C
Standard length : 36 yards

Note: The above are typical values obtained from tests recommended by the PSTC, ASTM, or government agencies and should not be used in writing specifications.